Version: A

2023-11-21

Specification for Approval

Customer:	
Model Name:	

Sı	upplier Approv	Customer approval	
R&D Designed	R&D Approved	QC Approved	
Peter	Peng Jun		



Version: A

2023-11-21

Revision Record

REV NO.	REV DATE	CONTENTS	Note
А	2023-11-21	NEW ISSUE	

2023-11-21

Table of Contents

List	Description	Page No.
	Cover	1
	Revision Record	2
	Table of Contents	3
1	Scope	4
2	General Information	4
3	External Dimensions	5
4	Interface Description	6
5	Absolute Maximum Ratings	8
6	DC Characteristics	8
7	Timing Characteristics	9
8	Backlight Characteristics	14
9	Optical Characteristics	15
10	Reliability Test Conditions and Methods	18
11	Inspection Standard	19
12	Handling Precautions	23
13	Precaution for Use	24
14	Packing Method	24



Version: A

2023-11-21

1. Scope

This specification defines general provisions as well as inspection standards for TFT module supplied by AMSON electronics.

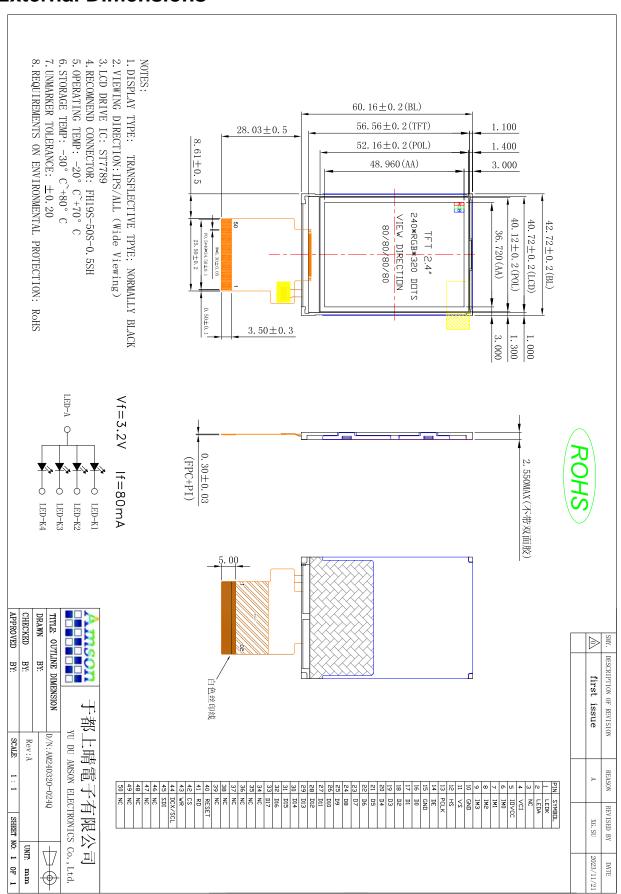
If the event of unforeseen problem or unspecified items may occur, naturally shall negotiate and agree to solution

2. General Information

ITEM	STANDARD VALUES	UNITS
LCD type	2.4"TFT	
Dot arrangement	240(RGB)×320	dots
Color filter array	RGB vertical stripe	
Display mode	Wide View + TF / Normally Black	-
Eyes Viewing Direction	80/80/80/80	
Driver IC	ST7789	
Module size	42.72 (W)×60.16(H)×2.55(T)	mm
Active area	36.72(W)×48.96(H)	mm
Dot pitch	0.153(W)×0.153(H)	mm
Interface	i80-system 8/16/18-bit MCU interface 3SPI/4SPI/ 16/18-bit RGB interface	
Operating temperature	-20 ~ +70	°C
Storage temperature	-30 ~ +80	°C
Back Light	4 White LED	

2023-11-21

3. External Dimensions





Version: A

2023-11-21

4. Interface Description

PIN NO.	PIN NAME	DESCRIPTION
1	LEDK	The cathode of LED power
2	LEDA	The Anode of LED power
3	NC	NC
4	VCI	Analog operating voltage.
5	IOVCC	Logic operating voltage.
6~9	IM0~IM3	MPU interface mode select pin,(FYI NOTE1)
10	GND	Power ground
11	VSYNC	Frame synchronizing signal for RGB interface operation.
12	HSYNC	Line synchronizing signal for RGB interface operation.
13	DOTCLK	Dot clock signal for RGB interface operation.
14	DE	Data enable signal for RGB interface operation.
15	GND	Power ground
16-33	DB0-DB17	Data bus
34`39	DB18~DB23	NC
40	RESET	Reset pin setting either pin low initializes the LSI Must be reset after power supplied
41	RD	Read signal input terminal, Active at 'L'.
42	CS	Chip select signal input terminal, Active at 'L'
43	/WR	Write enable in MCU parallel interface Display data/command selection pin in 4-line serial interface Second Data lane in 2 data lane serial interfaceIf not used, please fix this pin at VDDI or DGND.
44	DCX /SCL	Display data/command selection pin in parallel interface. This pin is used to be serial interface clock DCX='1': display data or parameter DCX='0': command data.
45	SDI	When IM [3]: Low, Serial in/out signal. When IM [3]: High, Serial input signal. The data is applied on the rising edge of the SCL signal.
46~50	NC	NC



Version: A

2023-11-21

Note1:

-The MCU interface mode select.

IM3	IM2	IM1	IM0	MPU Interface Mode	Data pin		
0	0	0	0	80-8bit parallel I/F	DB[7:0]		
0	0	0	1	80-16bit parallel I/F	DB[15:0]		
0	0	1	0	80-9bit parallel I/F	DB[8:0]		
0	0	1	1	80-18bit parallel I/F	DB[17:0],		
	1		4	3-line 9bit serial I/F	SDA: in/out		
0	1	0	1 2 data lane serial	2 data lana sarial I/E	SDA: in/out		
				2 data larie seriai i/F	2 data lane serial I/F		2 data lane senai //F
0	1	1	0	4-line 8bit serial I/F	SDA: in/out		
1	0	0	0	80-16bit parallel I/F ∐	DB[17:10],		
_ '	O	0	0	oo-Tobit parallel I/I II	DB[8:1]		
1	0	0	1	80-8bit parallel I/F Ⅱ	DB[17:10]		
1	0	1	0	80-18bit parallel I/F Ⅱ	DB[17:0],		
1	0	1	1	80-9bit parallel I/F Ⅱ	DB[17:9]		
1	1	0	1	3-line 9bit serial I/F Ⅱ	SDA: in/		
		U		3-IIIIe anit sellal I/L II	SDO: out		
1	1	1	0	4-line 8bit serial I/F Ⅱ	SDA:in/		
_ '	<u>'</u>	<u> </u>	U	4-IIIIe obit selial I/F II	SDO: out		

If not used, please fix this pin at VDDI or DGND.



Version: A

2023-11-21

5. Absolute Maximum Ratings

Item	Symbol	Min.	Max.	Unit
Logic Supply Voltage	IOVCC	-0.3	4.6	V
Analog Supply Voltage	VCI	-0.3	4.6	V
Input Voltage	Vin	-0.3	IOVCC +0.3	V
Operating Temperature	Тор	-20	70	°C
Storage Temperature	Тѕт	-30	80	°C
Storage Humidity	HD	20	90	%RH

6. DC Characteristics

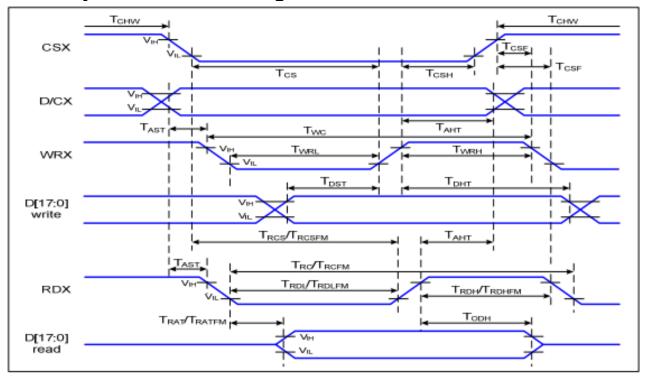
Symbol	Min.	Тур.	Max.	Unit	Remark
IOVCC	1.65	2.8	3.3	V	-
VCI	2.5	2.8	3.3	V	-
V _{IH}	0.7VCI	-	VCI	V	-
V _{IL}	GND	-	0.3 VCI	V	-
V _{OH}	0.8 VCI	-	VCI	V	-
V _{OL}	GND	-	0.2 VCI	V	-
ILI	-1	-	1	uA	-
IDD	-	7.0	15	mA	-
	IOVCC VCI VIH VIL VOH VOL ILI	IOVCC 1.65 VCI 2.5 V _{IH} 0.7VCI V _{IL} GND V _{OH} 0.8 VCI V _{OL} GND ILI -1	IOVCC 1.65 2.8 VCI 2.5 2.8 V _{IH} 0.7VCI - V _{IL} GND - V _{OH} 0.8 VCI - V _{OL} GND - ILI -1 -	IOVCC 1.65 2.8 3.3 VCI 2.5 2.8 3.3 V _{IH} 0.7VCI - VCI V _{IL} GND - 0.3 VCI V _{OH} 0.8 VCI - VCI V _{OL} GND - 0.2 VCI ILI -1 - 1	IOVCC 1.65 2.8 3.3 V VCI 2.5 2.8 3.3 V V _{IH} 0.7VCI - VCI V V _{IL} GND - 0.3 VCI V V _{OH} 0.8 VCI - VCI V V _{OL} GND - 0.2 VCI V ILI -1 - 1 uA

Version: A

2023-11-21

7. Timing Characteristics

7.1 i80-System Interface Timing Characteristics



Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T _{AST}	Address setup time	0		ns	
DICX	T _{AHT}	Address hold time (Write/Read)	10		ns	•
	T _{CHW}	Chip select "H" pulse width	0		ns	
	T _{CS}	Chip select setup time (Write)	15		ns	
CSX	T _{RCS}	Chip select setup time (Read ID)	45		ns	
CSA	T _{RCSFM}	Chip select setup time (Read FM)	355		ns	-
	T _{CSF}	Chip select wait time (Write/Read)	10		ns	
	T _{CSH}	Chip select hold time	10		ns	
	T _{wc}	Write cycle	66		ns	
WRX	T _{WRH}	Control pulse "H" duration	15		ns	
	T_{WRL}	Control pulse "L" duration	15		ns	
	T _{RC}	Read cycle (ID)	160		ns	
RDX (ID)	T_RDH	Control pulse "H" duration (ID)	90		ns	When read ID data
	T_{RDL}	Control pulse "L" duration (ID)	45		ns	
RDX	T _{RCFM}	Read cycle (FM)	450		ns	When read from
(FM)	T_{RDHFM}	Control pulse "H" duration (FM)	90		ns	frame memory
(FIVI)	T_{RDLFM}	Control pulse "L" duration (FM)	355		ns	name memory
D[17:0]	T _{DST}	Data setup time	10		ns	For CL=30pF

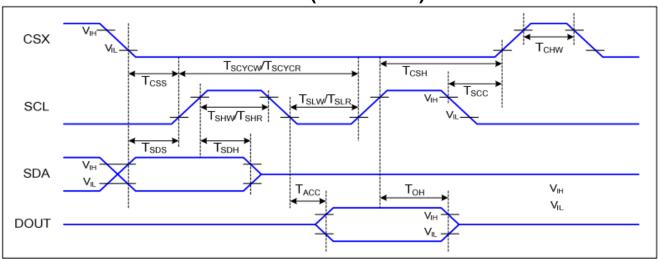


Version: A

2023-11-21

T _{DHT}	Data hold time	10		ns	
T _{RAT}	Read access time (ID)		40	ns	
T _{RATFM}	Read access time (FM)		340	ns	
T _{ODH}	Output disable time	20	80	ns	

7.2 Serial Interface Characteristics (3-line serial):

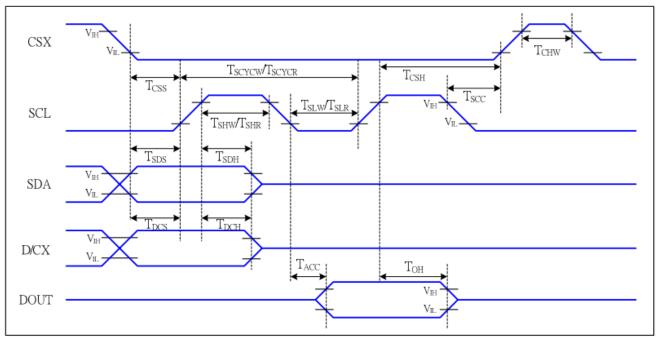


Signal	Symbol	Parameter	Min	Max	Unit	Description
	T _{CSS}	Chip select setup time (write)	15		ns	
	T _{CSH}	Chip select hold time (write)	15		ns	
CSX	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{scc}	Chip select hold time (read)	65		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
	T _{SCYCW}	Serial clock cycle (Write)	66		ns	
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	
SCL	T _{SLW}	SCL "L" pulse width (Write)	15		ns	
SCL	T _{SCYCR}	Serial clock cycle (Read)	150		ns	
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA	T _{SDS}	Data setup time	10		ns	
(DIN)	T _{SDH}	Data hold time	10		ns	
DOUT	T _{ACC}	Access time	10	50	ns	For maximum CL=30pF
DOUT	T _{OH}	Output disable time	15	50	ns	For minimum CL=8pF

Version: A

2023-11-21

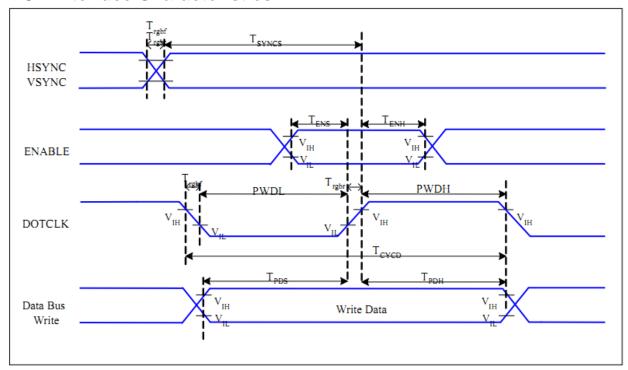
7.3 Serial Interface Characteristics (4-line serial):



Signal	Symbol	Parameter	MIN	MAX	Unit	Description
	T _{CSS} Chip select setup time (write)		15		ns	
	T _{CSH}	Chip select hold time (write)	15		ns	
CSX	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{SCC}	Chip select hold time (read)	65		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
	T _{SCYCW}	Serial clock cycle (Write)	66		ns	-write command & data
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	ram
SCL	T _{SLW}	SCL "L" pulse width (Write)	15		ns	Talli
SCL	T _{SCYCR}	Serial clock cycle (Read)	150		ns	read command 9 data
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	-read command & data
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	ram
D/CX	T _{DCS}	D/CX setup time	10		ns	
DICX	T _{DCH}	D/CX hold time	10		ns	
SDA	T _{SDS}	Data setup time	10		ns	
(DIN)	T _{SDH}	Data hold time	10		ns	
DOUT	T _{ACC}	Access time	10	50	ns	For maximum CL=30pF
DOOT	Тон	Output disable time	15	50	ns	For minimum CL=8pF

2023-11-21

7.4 RGB Interface Characteristics:



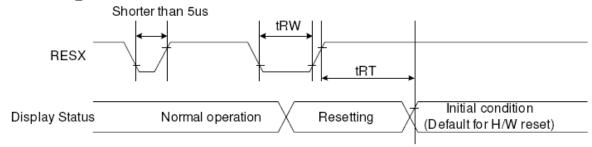
VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 ~ 70 $^{\circ}\mathrm{C}$

Signal	Symbol Parameter		MIN	MAX	Unit	Description
HSYNC,	T _{SYNCS}	VSYNC, HSYNC Setup Time	30		ns	
VSYNC	SYNCS	vorno, no mo setap nine	30	-	118	
ENABLE	T _{ENS}	Enable Setup Time	25	•	ns	
ENABLE	T _{ENH}	Enable Hold Time	25	-	ns	
	PWDH	DOTCLK High-level Pulse Width	60	-	ns	
DOTCLK	PWDL	DOTCLK Low-level Pulse Width	60	-	ns	
DOTOLK	T _{CYCD} DOTCLK Cycle Time		120	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	20	ns	
DB	T _{PDS}	PD Data Setup Time	50	-	ns	
DB	T _{PDH}	PD Data Hold Time	50	-	ns	

Table 7 18/16 Bits RGB Interface Timing Characteristics

2023-11-21

7.5 Reset Timing Characteristics



Signal	Symbol	Parameter	Min	Max	Unit
RESX	tRW	Reset pulse duration	10		uS
	tRT Reset cancel			5 (note 1,5)	mS
	thi	neset cancel		120 (note 1,6,7)	mS

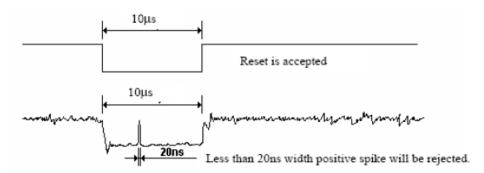
Note 1: The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NV memory to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

Note 2: Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below: -

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 10us	Reset
Between 5us and 10us	Reset starts

Note 3: During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In -mode.) And then return to Default condition for Hardware Reset.

Note 4: Spike Rejection also applies during a valid reset pulse as shown below:

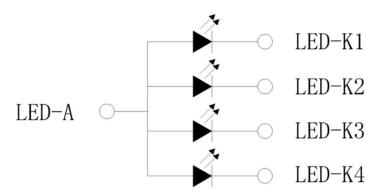


- Note 5: When Reset applied during Sleep In Mode.
- Note 6: When Reset applied during Sleep Out Mode.
- Note 7: It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

Version: A

2023-11-21

8. Backlight Characteristic



Item	Symbol	MIN	TYP	MAX	UNIT	Test Condition
Supply Voltage	Vf	2.9	3.2	3.5	V	If=80mA
Supply Current	If	-	80		mA	-
Luminous Intensity for LCM	-	100	150	-	cd/m ²	If=80mA
Uniformity for LCM	-	75	80	-	%	If=80mA
Life Time	-	20000	-	-	Hr	If=80mA
Backlight Color			\	White		

Version: A

2023-11-21

9. Optical Characteristics

9.1 Transmissive mode

Item	Condition	ıs	Min.	Тур.	Max.	Unit	Note	
	Horizontal	θL	60	80	1			
Viewing Angle	ПОПДОПІАІ	θR	60	80	ı	dograo	(1) (2) (6)	
(CR>10)	Vertical	θт	60	80	-	degree	(1),(2),(6)	
	v ei ileai	θв	60	80	-			
Contrast Ratio	Center		ı	300	ı	1	(1),(3),(6)	
Response Time	Rising + Falling		-	25	50	ms	(1),(4),(6)	
	Red x			0.633		-		
	Red y Green x Green y			0.320		-		
				0.292		1	Chromoticity	
CF Color				0.583D		-	Chromaticity measuring	
Chromaticity (CIE1931)	Blue x		Typ. -0.05	0.149	Typ. +0.05	ı	machine: CFT-01. Reference Only	
	Blue y		-0.03	0.127	10.03	-	Reference Offig	
	White x			0.298		-		
	White y		White y		0.327			-
NTSC	CIE1931		-	60	-	%	(1),(6)	

9.2 Reflective mode (Not driving the back light condition)

Item	Conditions	Min.	Тур.	Max.	Unit	Note	
Reflection Ratio (With Polarizer)	R (θ=0°)	-	5	-	%	Here the data are design value.	
Reflective Contrast Ratio	Cr (θ=φ=0°)	-	10	-	-	(1),(4),(6)	
	Θ21	-	45	-			
Viewing angle	Θ22	-	45	-	dog	Note1	
(Cr≥ 2)*	Θ12	-	45	-	deg	Note	
	Θ11	-	45	-			

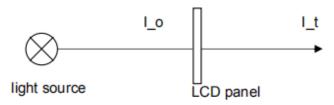
Note: Recommended backlight brightness of not more than 10000cd/m2.

2023-11-21

9.3 Definitions and measuring methods

[1]Transmittance (T%)

The transmittance of the panel including polarizer is measured with electrical driving.



The Transmittance is defined as:

$$Tr = \frac{I_{-}t}{I_{-}o} \times 100\%$$

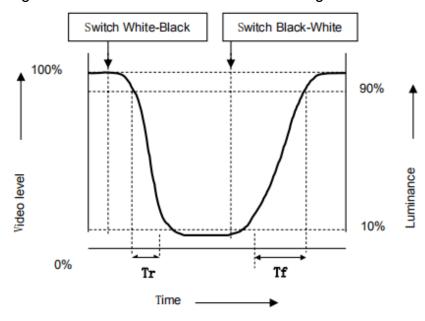
here.

I_o: the brightness of the light source.

I_t : the brightness after panel transmission.

[2] Response Time(Tr、Tf)

The rise time 'Tr' is defined as the time for luminance to change from 90% to 10% as a result of a change of the electrical condition. The fall time 'Tf' is defined as the time for luminance to change from 10% to 90% as a result of a change of the electrical condition.



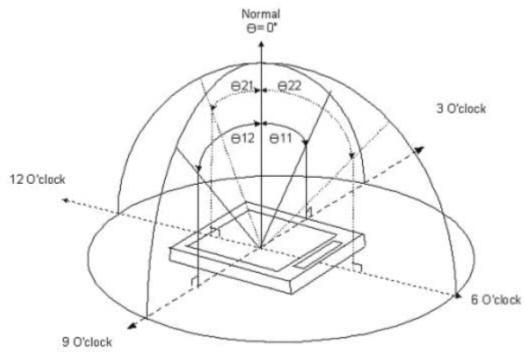
[3] Contrast ratio (Cr)

The contrast ratio (Cr), measured on a module, is the ratio between the luminance (L_w) in a full white area (R=G=B=1) and the luminance (L_d) in a dark area (R=G=B=0):

$$Cr = \frac{L - w}{L - d}$$

2023-11-21

[4] Viewing angle diagram



[5] Definition of color gamut

Measuring machine:CFT-01. NTSC' S Primaries: R(x,y,Y), G(x,y,Y), B(x,y,Y)

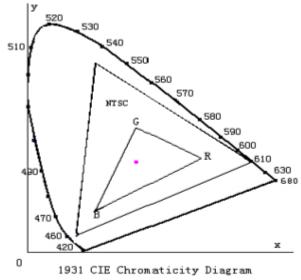


Fig. 1931 CIE chromaticity diagram

Color gamut: $S = \frac{\text{Area of RGB triangle}}{\text{Area of NTSC triangle}} \times 100\%$



Version: A

2023-11-21

10. Reliability Test Conditions and Methods

NO.	TEST ITEMS	TEST CONDITION	INSPECTION AFTER TEST
	High Temperature Storage	80°C±2°C×96Hours	
	Low Temperature Storage	-30°C±2°C×96Hours	
	High Temperature Operating	70°C±2°C×96Hours	Inonaction often 2. Abours
	Low Temperature Operating	-20°C±2°C×96Hours	Inspection after 2~4hours storage at room temperature, the samples
	Temperature Cycle(Storage)	-20°C \Longrightarrow 25°C \Longrightarrow 70°C (30min) (30min) 1cycle Total 10cycle	should be free from defects: 1, Air bubble in the LCD. 2, Seal leak. 3, Non-display. 4, Missing segments.
	Damp Proof Test (Storage)	50°C±5°C×90%RH×120Hours	5, Glass crack. 6, Current IDD is twice
	Vibration Test	Frequency:10Hz~55Hz~10Hz Amplitude:1.5MM X,Y,Z direction for total 3hours (packing condition test will be tested by a carton)	higher than initial value. 7, The surface shall be free from damage. 8, The electric characteristic requirements shall be satisfied.
	Drooping Test	Drop to the ground from 1M height one time every side of carton. (packing condition test will be tested by a carton)	Silali de Salislieu.
	ESD Test	Voltage:±8KV,R:330Ω,C:150PF,Air Mode,10times	

REMARK:

- 1, The Test samples should be applied to only one test item.
- 2, Sample side for each test item is 5~10pcs.
- 3,For Damp Proof Test, Pure water(Resistance $> 10M\Omega$)should be used.
- 4,In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.
- 5, EL evaluation should be accepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.
- 6, Failure Judgment Criterion: Basic Specification Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.



Version: A

2023-11-21

11. Inspection Standard

11.1. QUALITY:

THE QUALITY OF GOODS SUPPLIED TO PURCHASER SHALL COME UP TO THE FOLLOWING STANDARD.

11.1.1. THE METHOD OF PRESERVING GOODS

AFTER DELIVERY OF GOODS FROM AMSON TO PURCHASER. PURCHASER SHALL CONTROL THE LCM AT -10 °C TO 40 °C ,AND IT MIGHT BE DESIRABLE TO KEEP AT THE NORMAL ROOM TEMPERATURE AND HUMIDITY UNTIL INCOMING INSPECTION OR THROWING INTO PROCESS LINE.

11.1.2. INCOMING INSPECTION

(A) THE METHOD OF INSPECTION

IF PURCHASER MAKE AN INCOMING INSPECTION, A SAMPLING PLAN SHALL BE APPLIED ON THE CONDITION THAT QUALITY OF ONE DELIVERY SHALL BE REGARDED AS ONE LOT.

(B) THE STANDARD OF QUALITY

ISO-2859-1 (SAME AS MIL-STD-105E), LEVEL II SINGLE PLAN.

CLASS	AQL(%)
CRITICAL	0.4 %
MAJOR	0.65 %
MINOR	1.5 %
TOTAL	1.5 %

EVERY ITEM SHALL BE INSPECTED ACCORDING TO THE CLASS.

(C) MEASURE

IF AS THE RESULT OF ABOVE RECEIVING INSPECTION, A LOT OUT IS DISCOVERED. PURCHASER SHALL BE INFORM SELLER OF IT WITHIN SEVEN DAYS. BUT FIRST SHIPMENT WITHIN FOURTEEN DAYS.

11.1.3. WARRANTY POLICY

AMSON WILL PROVIDE ONE-YEAR WARRANTY FOR THE PRODUCTS ONLY IF UNDER SPECIFICATION OPERATING CONDITIONS. AMSON WILL REPLACE NEW PRODUCTS FOR THESE DEFECT PRODUCTS WHICH UNDER WARRANTY PERIOD AND BELONG TO THE RESPONSIBILITY OF AMSON.

11.2. CHECKING CONDITION

- 11.2.1. CHECKING DIRECTION SHALL BE IN THE 45 DEGREE AREA TO FACE THE SAMPLE.
- 11.2.2. CHECKER SHALL SEE OVER 300±25 mm. WITH BARE EYES FAR FROM SAMPLE AND USING 2 PCS. OF 20W FLUORESCENT LAMP.



Version: A

2023-11-21

11.3. INSPECTION PLAN:

11.5. INST EO	TION TEAN.		
CLASS	ITEM	JUDGEMENT	CLASS
	1. OUTSIDE AND INSIDE PACKAGE	"MODEL NO.", "LOT NO." AND "QUANTITY"	Minor
PACKING &		SHOULD INDICATE ON THE PACKAGE.	
INDICATE	2. MODEL MIXED AND QUANTITY	OTHER MODEL MIXEDREJECTED	Critical
		QUANTITY SHORT OR OVERREJECTED	
	3. PRODUCT INDICATION	"MODEL NO." SHOULD INDICATE ON	Major
		THE PRODUCT	
	4. DIMENSION,	ACCORDING TO SPECIFICATION OR	
ASSEMBLY	LCD GLASS SCRATCH	DRAWING.	Major
	AND SCRIBE DEFECT.		,
	5. VIEWING AREA	POLARIZER EDGE OR LCD'S SEALING LINE	Minor
		IS VISABLE IN THE VIEWING AREA	
		REJECTED	
	6. BLEMISH - BLACK SPOT -	ACCORDING TO STANDARD OF VISUAL	Minor
	WHITE SPOT IN THE LCD	INSPECTION(INSIDE VIEWING AREA)	
	AND LCD GLASS CRACKS		
	7. BLEMISH - BLACK SPOT	ACCORDING TO STANDARD OF VISUAL	Minor
APPEARANCE	WHITE SPOT AND SCRATCH	INSPECTION(INSIDE VIEWING AREA)	
	ON THE POLARIZER		
	8. BUBBLE IN POLARIZER	ACCORDING TO STANDARD OF VISUAL	Minor
		INSPECTION(INSIDE VIEWING AREA)	
	9. LCD'S RAINBOW COLOR	STRONG DEVIATION COLOR (OR NEWTON	
		RING) OF LCDREJECTED.	Minor
		OR ACCORDING TO LIMITED SAMPLE	
		(IF NEEDED, AND INSIDE VIEWING AREA)	
	10. ELECTRICAL AND OPTICAL	ACCORDING TO SPECIFICATION OR	Critical
	CHARACTERISTICS	DRAWING . (INSIDE VIEWING AREA)	
	(CONTRAST: VOP:		
	CHROMATICITY ETC)		
ELECTRICAL	11.MISSING LINE	MISSING DOT: LINE : CHARACTER	Critical
		REJECTED	
	12.SHORT CIRCUIT	NO DISPLAY - WRONG PATTERN	Critical
	WRONG PATTERN DISPLAY	DISPLAY - CURRENT CONSUMPTION	
		OUT OF SPECIFICATION REJECTED	
	13. DOT DEFECT (FOR COLOR AND TFT)	ACCORDING TO STANDARD OF VISUAL	Minor
		INSPECTION	



Version: A

2023-11-21

11.4	STAN	DARD OF VISUAL INSPECT	F VISUAL INSPECTION							
NO.	CLASS	ITEM	JUDGEMENT							
			(A) ROUND TYPE: unit : mm.							
			DIAMETER (mm.) ACCEPTABLE Q'TY							
			$\Phi \leq 0.1$ DISREGARD							
		BLACK AND WHITE SPOT	$0.1 < \Phi \leq 0.25$ 3 (Distance>5mm)							
		FOREIGN MATERIEL	0.25 < Φ 0							
11.4.1	MINOR	DUST IN THE CELL	NOTE: Φ =(LENGTH+WIDTH)/2 (B) LINEAR TYPE: unit : mm.							
		BLEMISH	LENGTH WIDTH ACCEPTABLE Q'TY							
		SCRATCH	W ≤0.03 DISREGARD							
			L ≤ 5.0 0.03 < W ≤ 0.07 3 (Distance>5mm)							
			0.07 < W FOLLOW ROUND TYPE							
			i ozen kosko i i z							
			unit : mm.							
			DIAMETER ACCEPTABLE Q'TY							
	MINOR	BUBBLE IN POLARIZER	$\Phi \leq 0.2$ DISREGARD							
11.4.2		DENT ON POLARIZER	$0.2 < \Phi \leq 0.5$ 2 (Distance>5mm)							
			0.5 < Φ 0							
			Items ACC. Q'TY							
		Dot Defect	Bright dot N≤ 4							
			Dark dot N≤ 4							
11.4.3	MINOR		Pixel Define: Pixel Pixel Pixel Pixel Pixel Pixel Pot Dot Dot Note 1: The definition of dot: The size of a defective dot over 1/2 of whole dot is regarded as one defective dot. Note 2: Bright dot: Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern. Note 3: Dark dot: Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green ,blue pattern.							



Version: A

2023-11-21

NO.	CLASS	ITEM	JUDGEMEN	Т
11.4.4	MINOR	LCD GLASS CHIPPING	S	Y > S Reject
11.4.5	MINOR	LCD GLASS CHIPPING	SX	X or Y > S Reject
11.4.6	MAJOR	LCD GLASS GLASS CRACK	Y Y	Y > (1/2) T Reject
11.4.7	MAJOR	LCD GLASS SCRIBE DEFECT	A + B	 a> L/3 , A>1.5mm. Reject B: ACCORDING TO DIMENSION
11.4.8	MINOR	LCD GLASS CHIPPING (ON THE TERMINAL AREA)	T	Φ = (x+y)/2 > 2.5 mm Reject
11.4.9	MINOR	LCD GLASS CHIPPING (ON THE TERMINAL SURFACE)	TZX	Y > (1/3) T Reject
11.4.10	MINOR	LCD GLASS CHIPPING	T Z	Y > T Reject



Version: A

2023-11-21

12. Handling Precautions

12.1 Mounting method

The LCD panel of AMSON TFT module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[Recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (CI), Sulfur (S)

If goods were sent without being silicon coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Sulfur (S) from customer, Responsibility is on customer.

12.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to POWER or GROUND, do not input any signals before power is turned on, and ground your body, work/assembly areas, and assembly equipment to protect against static electricity.

12.4 packing

- Module employs LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

12.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.



Version: A

2023-11-21

Usage under the maximum operating temperature, 50%Rh or less is required.

12.6 storing

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it. And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
 [It is recommended to store them as they have been contained in the inner container at the time of delivery from us

12.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water

13. Precaution for Use

13.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification
- When a new problem is arisen which is not specified in this specifications
- When an inspection specifications change or operating condition change in customer is reported to AMSON TFT, and some problem is arisen in this specification due to the change
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

14. Packing Method

TBD